

Fig. 1

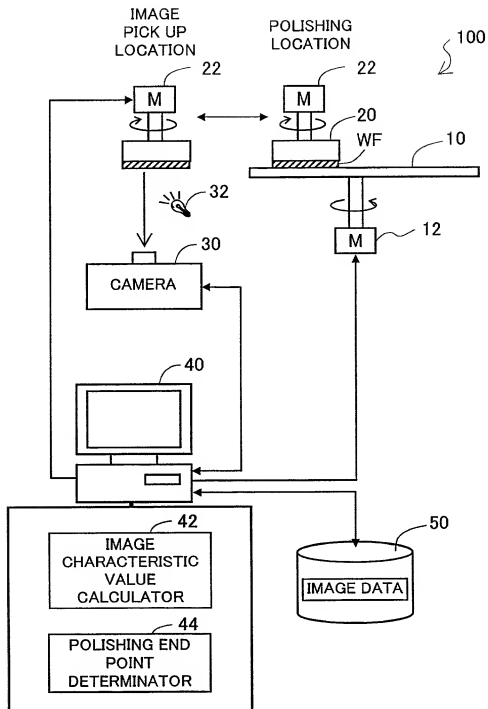
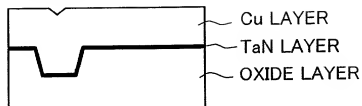


Fig.2A FORMING Cu LAYER



REMOVING Cu LAYER

Fig.2B FIRST CMP PROCESS



DELETING TaN  
SURFACE LAYER

Fig.2C SECOND CMP PROCESS



Fig. 3

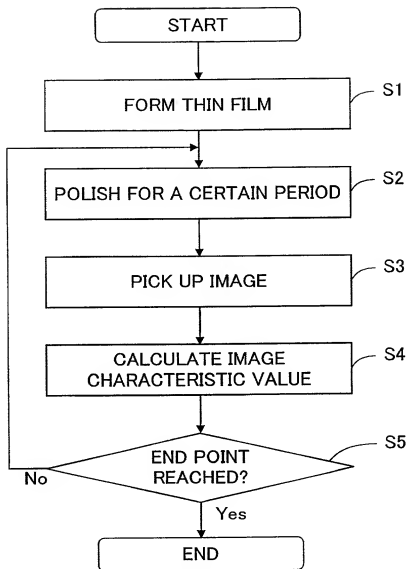


Fig. 4A

BEFORE POLISHING

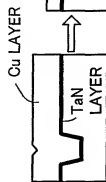


Fig. 4B

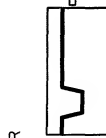
PLANARIZING  
Cu LAYER

Fig. 4C

STARTING TO  
DETECT WIRING  
PATTERN

Fig. 4D

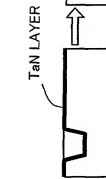
APPROPRIATE  
POLISHING

Fig. 4E

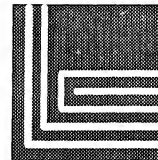
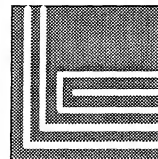
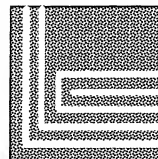
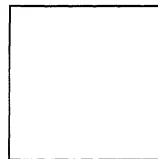
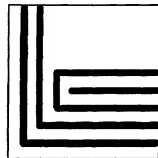
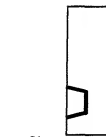
EXCESSIVE  
POLISHING

Fig. 5

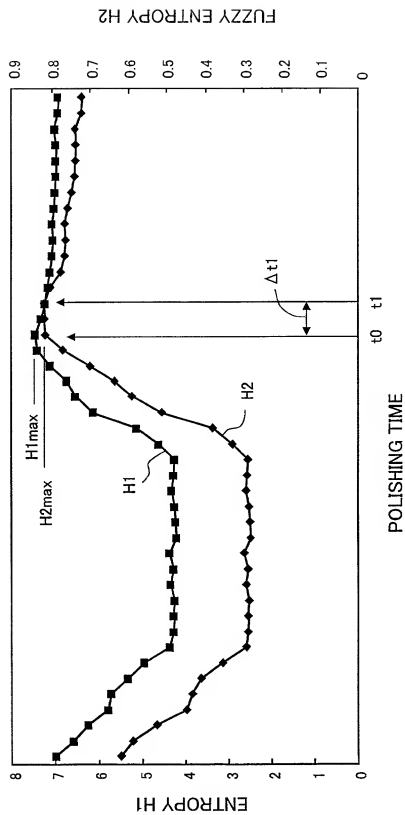
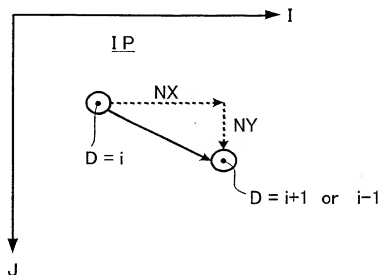


Fig. 6

CALCULATION OF HISTOGRAMS  $G(i)$ ,  
 $P(i)$  USED IN DIFFERENCE STATISTIC  
 OF GRAY IMAGE



HYSTOGRAM  $G(i)$ :

Probability that an absolute value of a difference of image values  $D$  of two pixels separated by  $(NX, NY)$  has a value of  $i$ .

$$P(i) = G(i+1)$$

Fig. 7

